

描述 / Descriptions

表面贴装整流二极管，反向电压：800~1000V，正向电流：8.0A，SMC 封装。
Surface Mount General Purpose Silicon Rectifier, Reverse Voltage: 800 to 1000 V, Forward Current: 8.0A, SMC package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟RoHS指令2011/65/EU，适用于表面贴装，无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications, Halogen free product.

用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

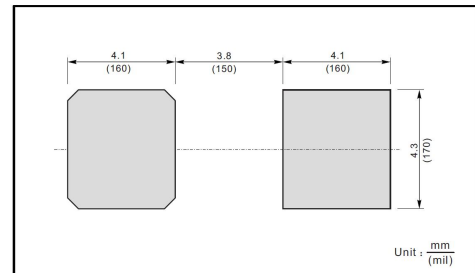


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating		单位 Unit
		S8KC	S8MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	8.0		A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	200		A
Typical Junction Capacitance ¹⁾	C_i	40		pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	35		°C/W
	$R_{\theta JC}$	13		
Operating Junction Temperature Range	T_j	-55~+150		°C
Storage Temperature Range	T_{stg}	-55~+150		°C

Note:

- 1) Measured at 1MHz and applied reverse voltage of 4 V D.C.
- 2) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating		单位 Unit
			S8KC	S8MC	
Max Instantaneous Forward Voltage	V_F	$I_F=8.0A$	0.985		V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$	10		uA
		$T_a=125^\circ C$	250		

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

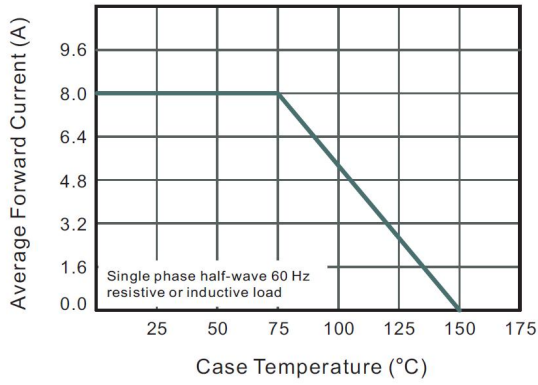


Fig.2 Typical Reverse Characteristics

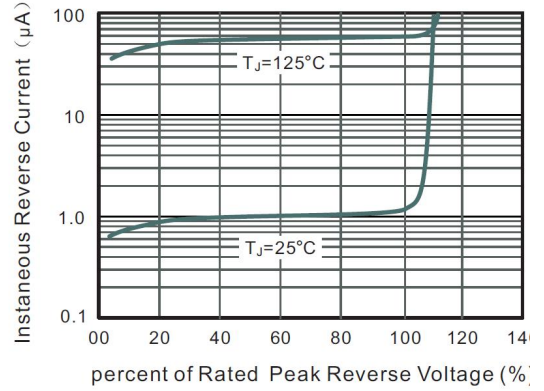


Fig.3 Typical Forward Characteristic

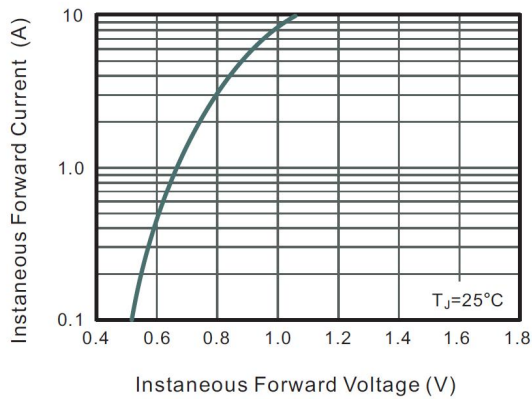


Fig.4 Typical Junction Capacitance

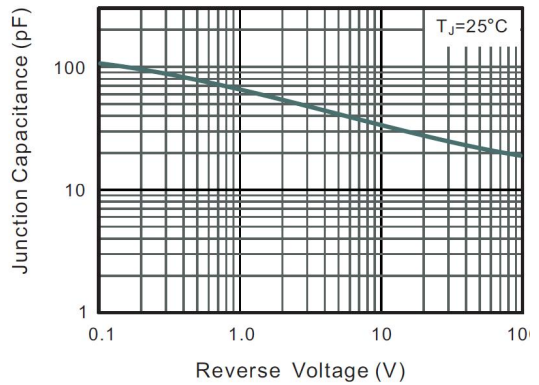
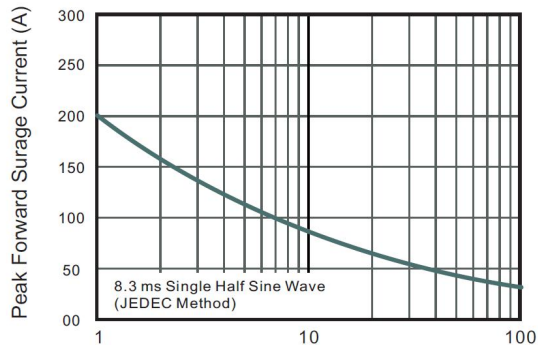
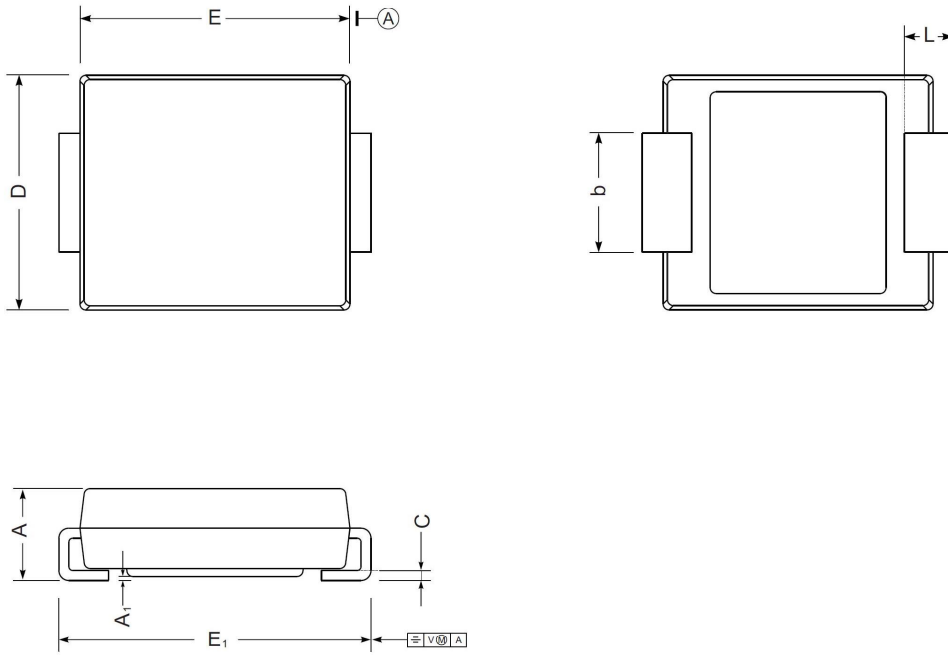


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

SMC



SMC mechanical data

UNIT		A	E	D	E ₁	A ₁	C	L	b
mm	max	2.62	7.0	6.2	8.0	0.21	0.31	1.6	3.25
	min	2.00	6.5	5.6	7.6	0.05	0.15	0.9	2.75
mil	max	103	276	244	315	8.3	12	63	128
	min	79	256	220	299	2.0	5.9	35	108

Marking

Type number	Marking code
S8KC	S8K
S8MC	S8M

印章说明 / Marking Instructions



说明

S8K : 为型号代码

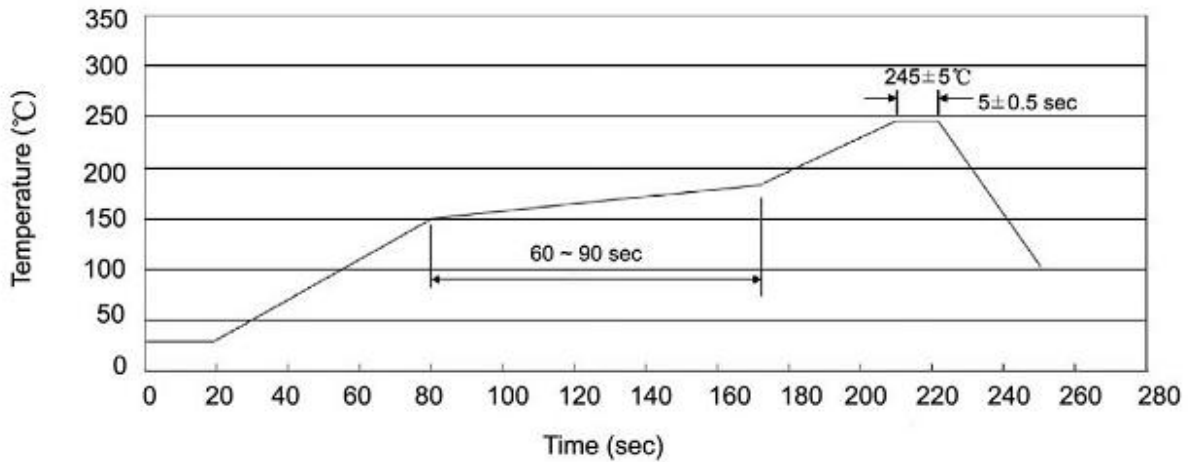
**** : 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

S8K : Product Type Code

**** : Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No
Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMC	3000	2	6000	6	36000	13" ×16	337X337X49	380X335X366

使用说明 / Notices